OSRAM SFH 4171 **Datasheet**

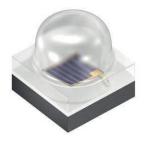




OSLON® P1616 Lens

SFH 4171

High Power Infrared Emitter (850 nm)









Applications

- Access Control (IRIS/Vein Scan, Face Recognition)
- Eye Tracking

- Gesture Recognition
- Safety and Security, CCTV

Features

- Package: clear silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)
- IR lightsource with high efficiency
- Centroid wavelength 850 nm



Ordering Information

Radiant intensity 1)2) Type Radiant intensity 1) Ordering Code $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ $I_{F} = 1 \text{ A}; t_{p} = 10 \text{ ms}$ SFH 4171 320 ... 500 mW/sr 400 mW/sr Q65113A3397



Maximum Ratings

T_A = 25 °C

Parameter	Symbol		Values
Operating temperature	T_{op}	min.	-40 °C
	op.	max.	105 °C
Storage temperature	T _{stg}	min.	-40 °C
	olg	max.	105 °C
Junction temperature	T_{j}	max.	145 °C
Forward current	I _F	max.	1000 mA
Forward current pulsed	 F pulse	max.	1000 mA
Reverse voltage 3)	V_R	max.	5 V
Power consumption	P _{tot}	max.	2300 mW
ESD withstand voltage	V_{ESD}	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	200		

Note: For the forward current and power consumption please see "maximum permissible forward current" diagram.



Characteristics

 $I_{\scriptscriptstyle F}$ = 1000 mA; $t_{\scriptscriptstyle p}$ = 10 ms; $T_{\scriptscriptstyle A}$ = 25 °C

Parameter	Symbol		Values
Peak wavelength	λ_{peak}	typ.	860 nm
Centroid wavelength	$\lambda_{ ext{centroid}}$	typ.	850 nm
Spectral bandwidth at 50% I _{rel,max} (FWHM)	Δλ	typ.	34 nm
Half angle	φ	typ.	35 °
Dimensions of chip area	LxW	typ.	0.73 x 0.73 mm x mm
Rise time (10% / 90%) $I_F = 1 \text{ A}; R_L = 50 \Omega$	t _r	typ.	11 ns
Fall time (10% / 90%) $I_F = 1 \text{ A}; R_L = 50 \Omega$	t _f	typ.	15 ns
Forward voltage 4)	V_{F}	typ. max.	1.75 V 2.20 V
Reverse current 3)	I _R	typ. max.	0.01 μA 10 μA
Total radiant flux 5)	Фе	typ.	700 mW
Temperature coefficient of voltage	TC _v	typ.	-1 mV / K
Temperature coefficient of brightness	TC	typ.	-0.3 % / K
Temperature coefficient of wavelength	TC _λ	typ.	0.3 nm / K
Thermal resistance junction solder point real 6)	$R_{thJSreal}$	max.	13 K / W

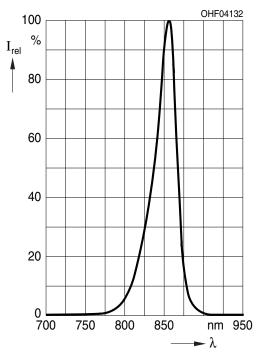


Brightness Groups

Group	Radiant intensity 1)2)	Radiant intensity 1)2)	
	$I_F = 1 \text{ A; } t_p = 10 \text{ ms}$ min.	$I_{p} = 1 \text{ A}; t_{p} = 10 \text{ ms}$	
		max. I _e	
CA2	320 mW/sr	355 mW/sr	
CB1	355 mW/sr	400 mW/sr	
CB2	400 mW/sr	450 mW/sr	
DA1	450 mW/sr	500 mW/sr	

Relative Spectral Emission 7), 8)

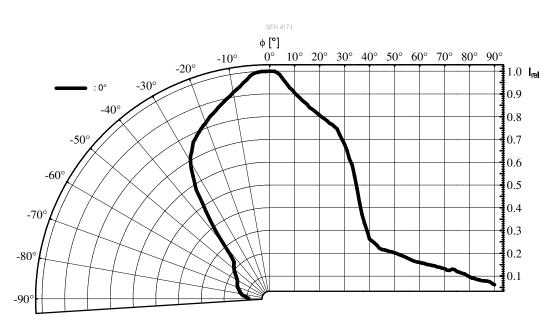
 $I_{e,rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$





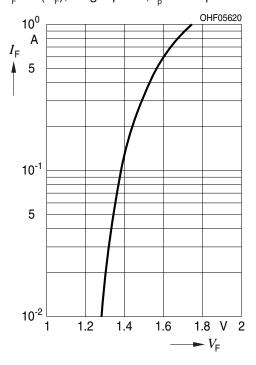
Radiation Characteristics 7), 8)

$$I_{e,rel} = f(\phi)$$



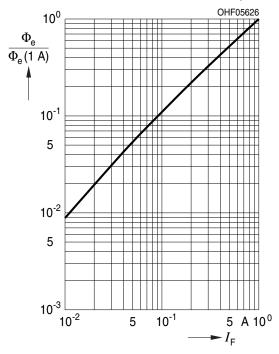
Forward current 7), 8)

 $I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



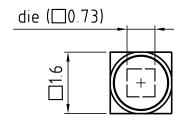
Relative Total Radiant Flux 7), 8)

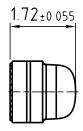
 Φ_e/Φ_e (1000mA) = f (I_F); single pulse; t₀ = 100 µs

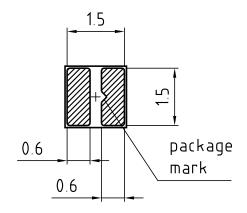




Dimensional Drawing 9)







general tolerance ± 0.05 lead finish Au ZZZZ

C63062-A4399-A3...-02

Further Information:

Approximate Weight: 7.6 mg

Package marking: Cathode

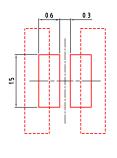
Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

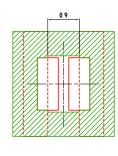
60068-2-43)



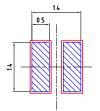
Recommended Solder Pad 9)

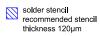


















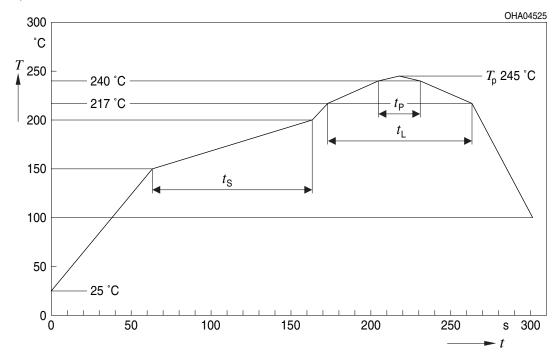


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Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



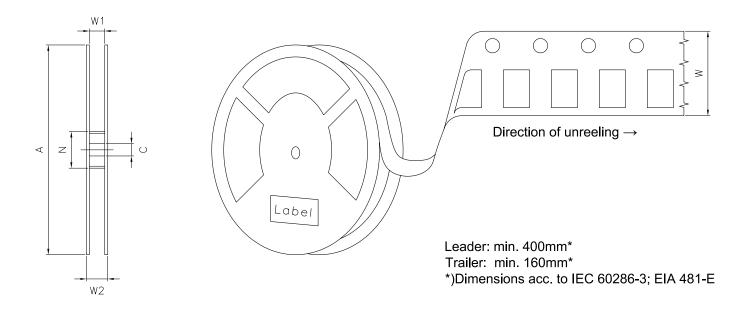
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assemb			nbly Unit	
		Minimum	Recommendation	Maximum		
Ramp-up rate to preheat*)			2	3	K/s	
25 °C to 150 °C						
Time t _s	t _s	60	100	120	S	
T_{Smin} to T_{Smax}						
Ramp-up rate to peak*)			2	3	K/s	
T_{Smax} to T_{P}						
Liquidus temperature	T_L		217		°C	
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S	
Peak temperature	T _P		245	260	°C	
Time within 5 °C of the specified peak temperature T_p - 5 K	t _P	10	20	30	S	
Ramp-down rate*			3	6	K/s	
T _P to 100 °C			-			
Time				480	S	
25 °C to T _P						

All temperatures refer to the center of the package, measured on the top of the component

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



Tape and Reel 10)



Reel Dimensions

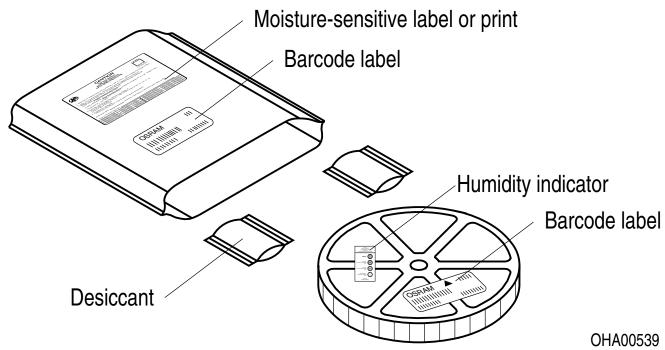
Α	W	N_{\min}	W_1	$W_{2 max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

Handling:

Solvents, water, liquids, non-conductive plastics and glues are not allowed near the device, because solvents and other liquids could emerge and damage the product.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



Glossary

- 1) **Radiant intensity:** Measured at a solid angle of Ω = 0.01 sr
- 2) **Brightness:** The brightness values are measured with a tolerance of ±11%.
- 3) Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Forward Voltage: The forward voltages are measured with a tolerance of ±0.1 V.
- 5) Total radiant flux: Measured with integrating sphere.
- 6) Thermal resistance: junction - soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- 7) Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) **Testing temperature:** TA = 25°C (unless otherwise specified)
- 9) Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

SFH 4171 DATASHEET



Revision History

Version	Date	Change
1.0	2022-03-07	Initial Version



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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